

# Chip War

Implications for Japan  
and Industrial Policy

January, 2023

Chris Miller



# Executive Summary

1. How Semiconductors Have Shaped the World Order
2. Russia, Ukraine and the Future of High-Tech Warfare
3. The China Chip Choke
4. How Supply Chains are Shifting
5. How the Chip Industry is Changing
6. Implications for Japanese Industry

# 1. How Semiconductors Have Shaped the World Order

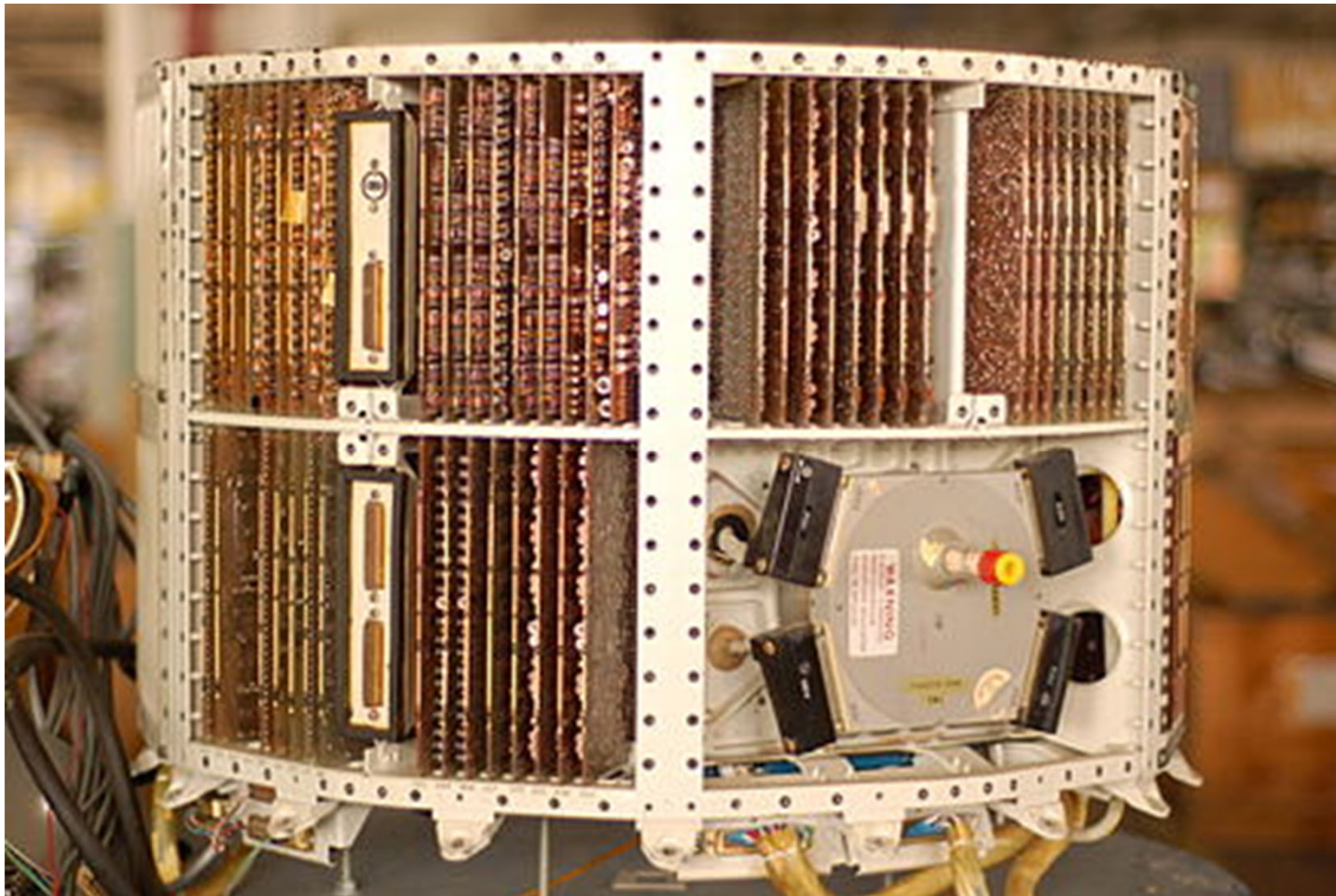
**The chip industry emerged from the Cold War arms race, requiring computers small enough to fit in missiles**



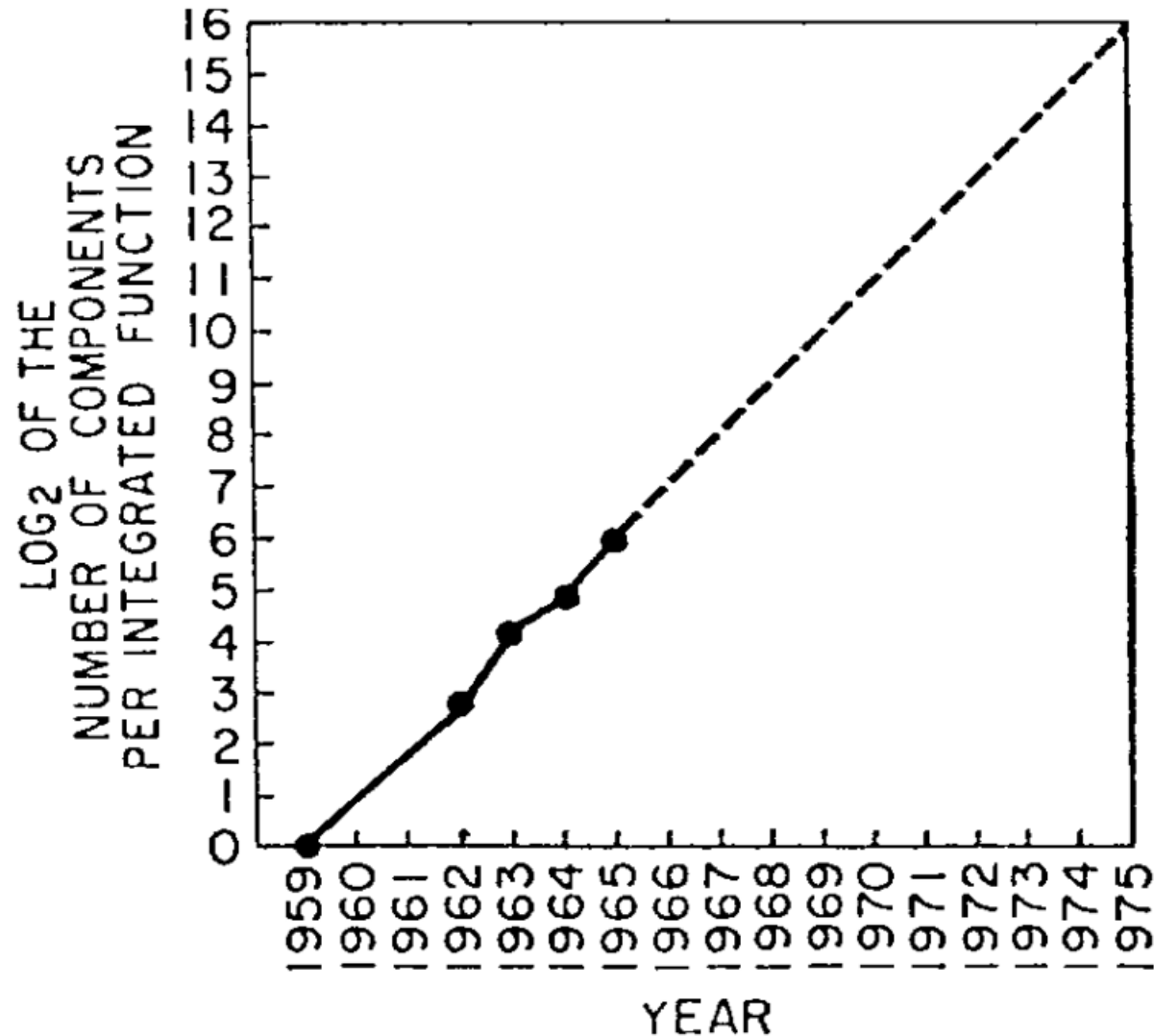


# The first major chip contracts were for NASA rockets and nuclear missiles

Minuteman ICBM Guidance Computer



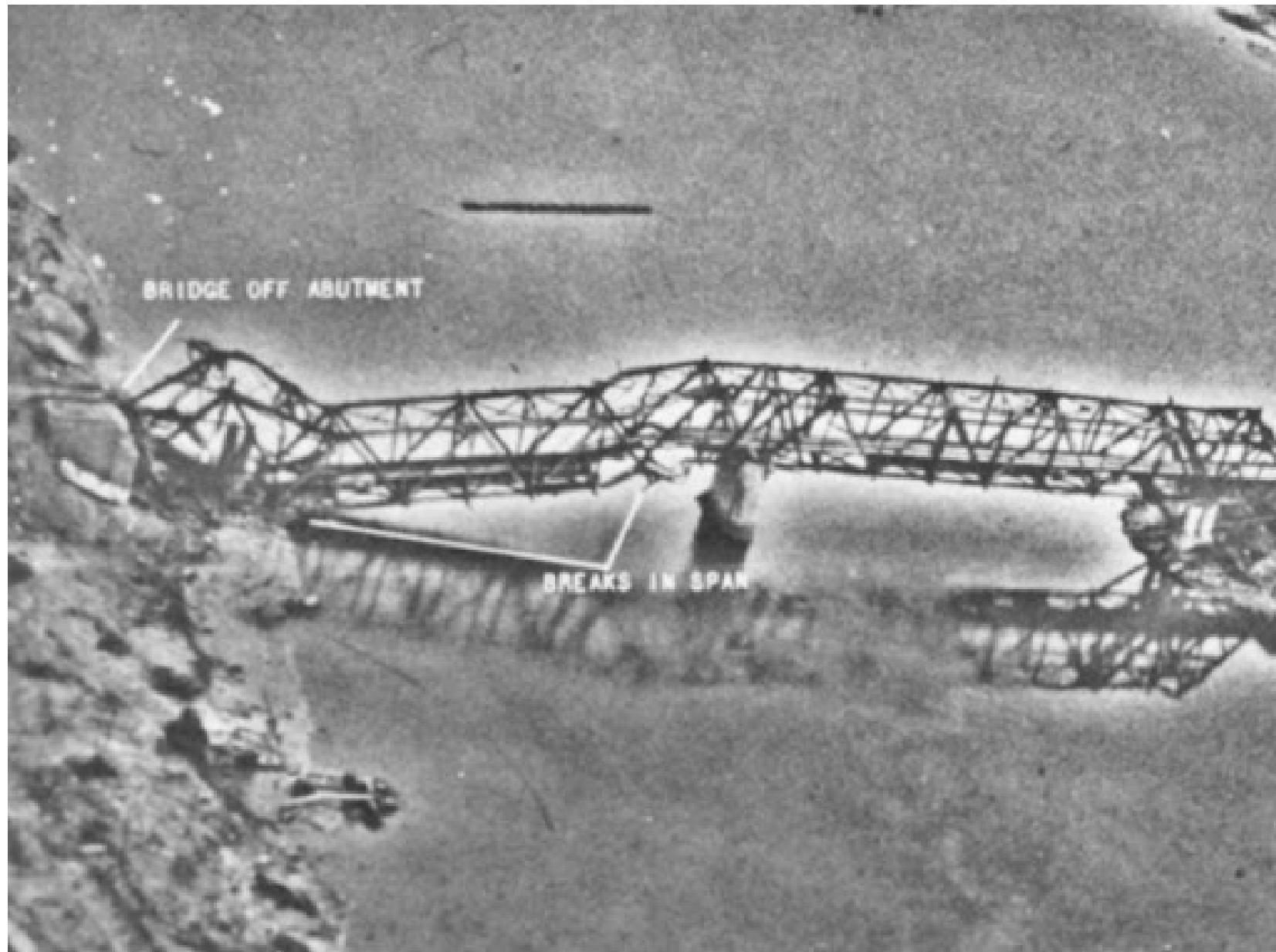
**In 1965, Gordon Moore noted that computing power was growing exponentially**



# Allowing computing power to be deployed in all manner of devices



**This facilitated revolutionary changes in military tactics**



## 2. Russia, Ukraine and the Future of High-Tech Warfare



# Today, governments are interested because chips are crucial to today's military systems



Western powers have sent hundreds of Javelin anti-tank missiles to Ukraine. Each one has over 200 semiconductors inside.

# Ukraine is succeeding in part by its innovative use of high tech, semiconductor-enabled systems

Starlink low earth orbit satellites have helped Ukraine communicate throughout the war





# Ukraine can strike targets with precision deep behind the front lines

HIMARs systems have transformed the war by combining satellite guidance with U.S.-provided signals intelligence



# Many of Russia's cyber attacks were thwarted by Ukraine's defenses—with help from Microsoft and Google



# Future warfare will only be more reliant on computing, sensing, and communications



DARPA visualization of future military systems, heavily networked, using advance sensors, deploying electronic warfare and directed energy weapons.



**It will also rely on autonomous systems, requiring AI training in data centers plus powerful edge processing**



China's GJ-11 Drone

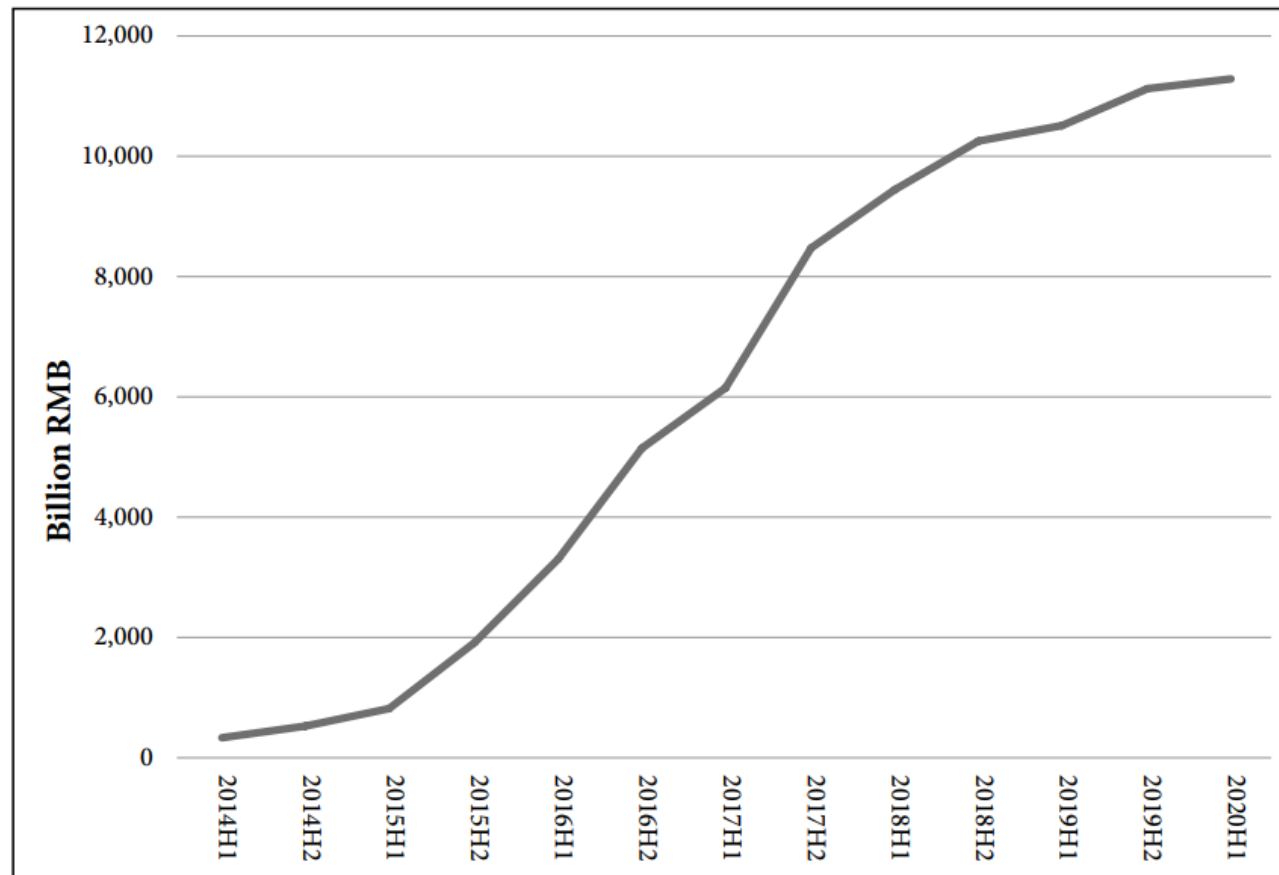
### 3. The China Chip Choke

# Though China's military depends on chips, its semiconductor industry is comparatively small

	Segment Value add	Market shares						
		U.S.	S. Korea	Japan	Taiwan	Europe	China	Other
EDA	1.5%	96%	<1%	3%	0%	0%	<1%	0%
Core IP	0.9%	52%	0%	0%	1%	43%	2%	2%
Wafers	2.5%	0%	10%	56%	16%	14%	4%	0%
Fab tools	14.9%	44%	2%	29%	<1%	23%	1%	1%
ATP tools	2.4%	23%	9%	44%	3%	6%	9%	7%
Design	29.8%	47%	19%	10%	6%	10%	5%	3%
Fab	38.4%	33%	22%	10%	19%	8%	7%	1%
ATP	9.6%	28%	13%	7%	29%	5%	14%	4%
Total value add		39%	16%	14%	12%	11%	6%	2%

# China has poured government funds into its chip industry...

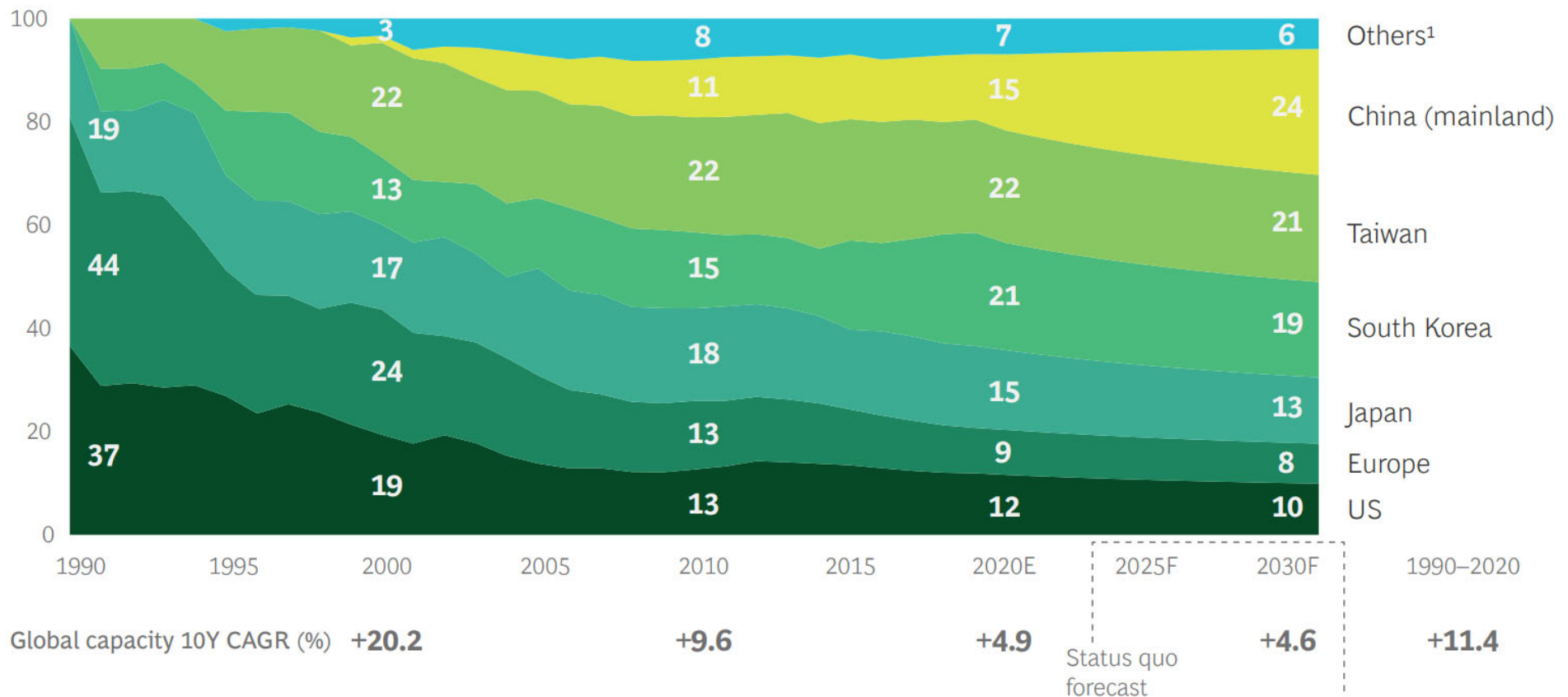
Figure 4.1: Government Industrial Guidance Funds: Cumulative Fund-Raising Scope





# But most of the money is going to build out low-end fabrication capacity

Global manufacturing capacity by location (%)



# China remains hugely reliant on imported machines and components

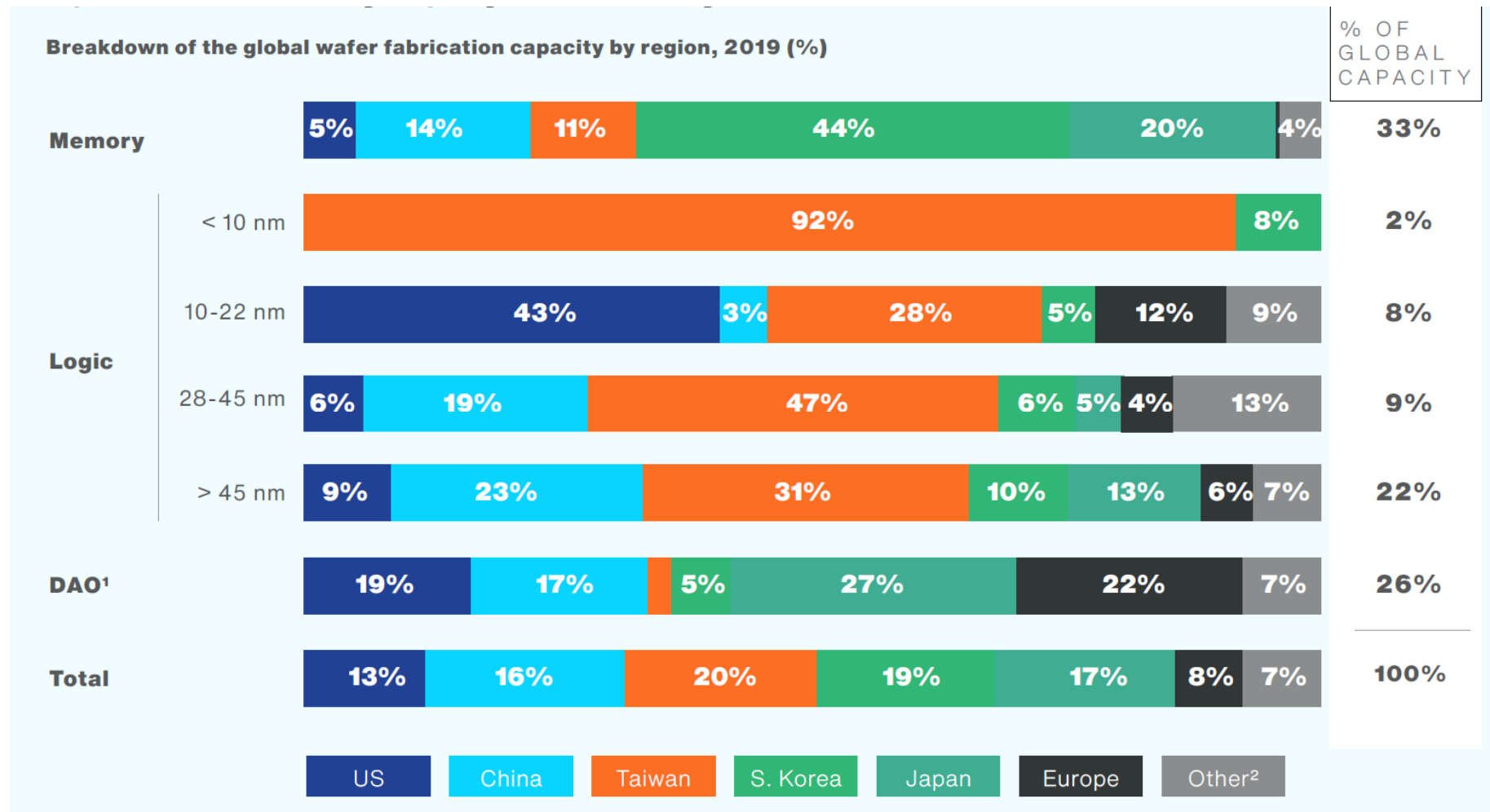
Today, China relies extensively on imports in the following areas:

- Chip design software
- Chip designs (though these capabilities are improving)
- Advanced processor and DRAM logic chips
- Most types of chipmaking machinery
- Many types of ultra-purified chemicals and materials

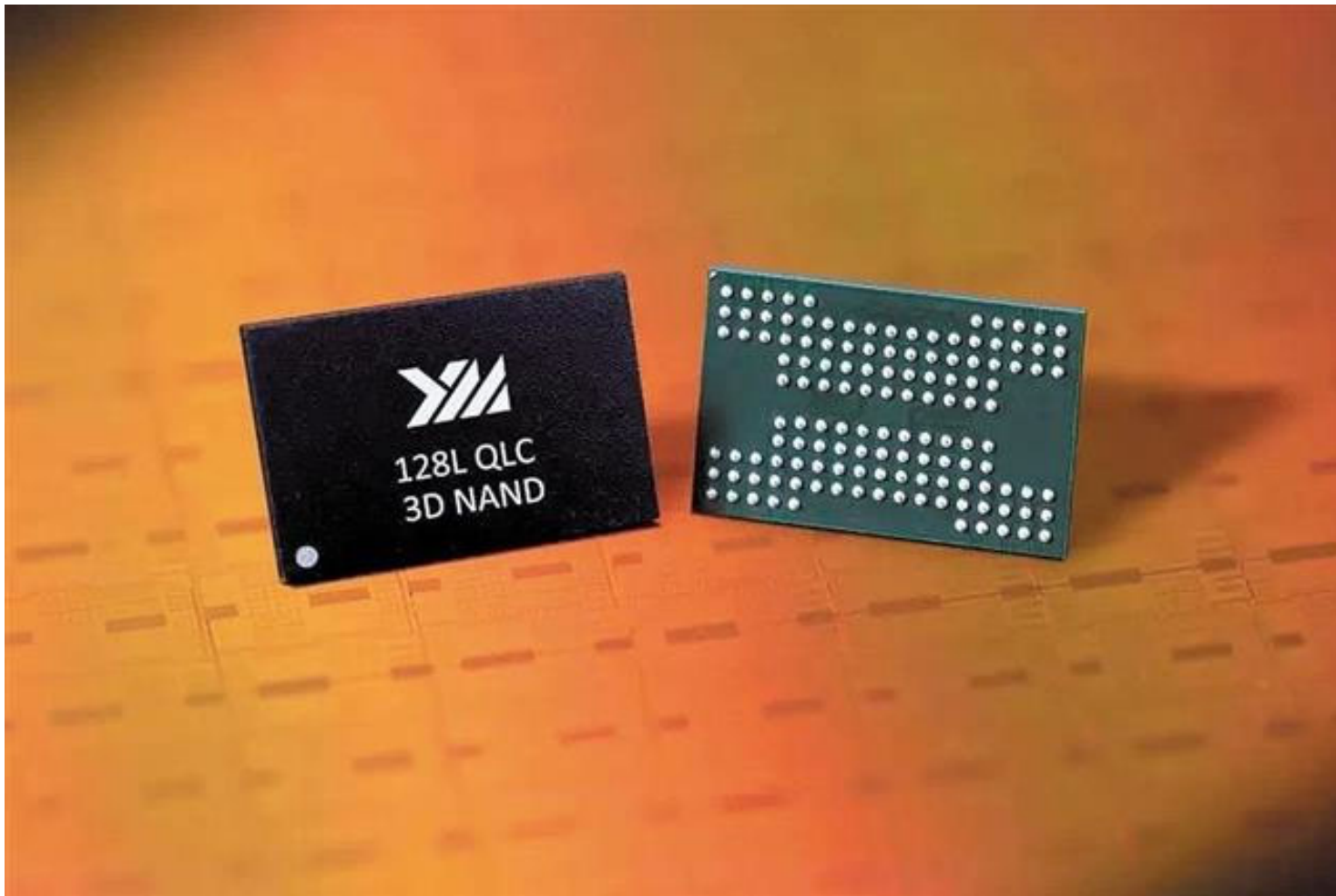
Table 3: China's competitiveness across supply chain segments

R&D	Lithography tools	Assembly & pkg tools	CMP tools
	EUV scanners	Assembly inspection	
Design	ArF immersion scanners	Dicing	Ion implanters
Logic chips	ArF dry scanners	Bonding	Low current
CPUs (logic)	KrF steppers	Packaging	High current
GPUs (logic)	i-line steppers	Integrated assembly	High voltage
FPGAs (logic)	Mask aligners		Ultra high dose
AI ASICs (logic)	E-beam lithography	Testing tools	
DRAM (memory)	Laser lithography	Memory	EDA software
NAND (memory)	Ion beam lithography	System-on-a-chip	
Analog chips	Imprint lithography	Burn-in	Core IP
OSD	Resist processing	Linear & discrete	
		Handlers & probes	Raw Materials
Fab	Deposition tools		
Logic chips	Chemical vapor deposition	Wafer and mask tools	Fab materials
Logic foundry	Physical vapor deposition	Wafer manufacturing	Wafers
Logic IDM	Rapid thermal processing	Wafer & mask handling	Photoresists
Advanced logic	Tube-based diffusion & dep.	Wafer marking	Photomasks
Memory chips	Spin coating		CMP slurries & pads
Analog chips	Electrochemical deposition	Process control tools	Deposition
Optoelectronics		Wafer inspection	Electronic Gases
Sensors	Etch & clean tools	Photomask inspection	Wet chemicals
Discretes	Dry etch and clean	Wafer level pkg inspect.	
	Atomic layer etch	Process monitoring	Packaging materials
ATP	Wet etch and clean		

# And the entire world depends on advanced fabrication from Taiwan and South Korea



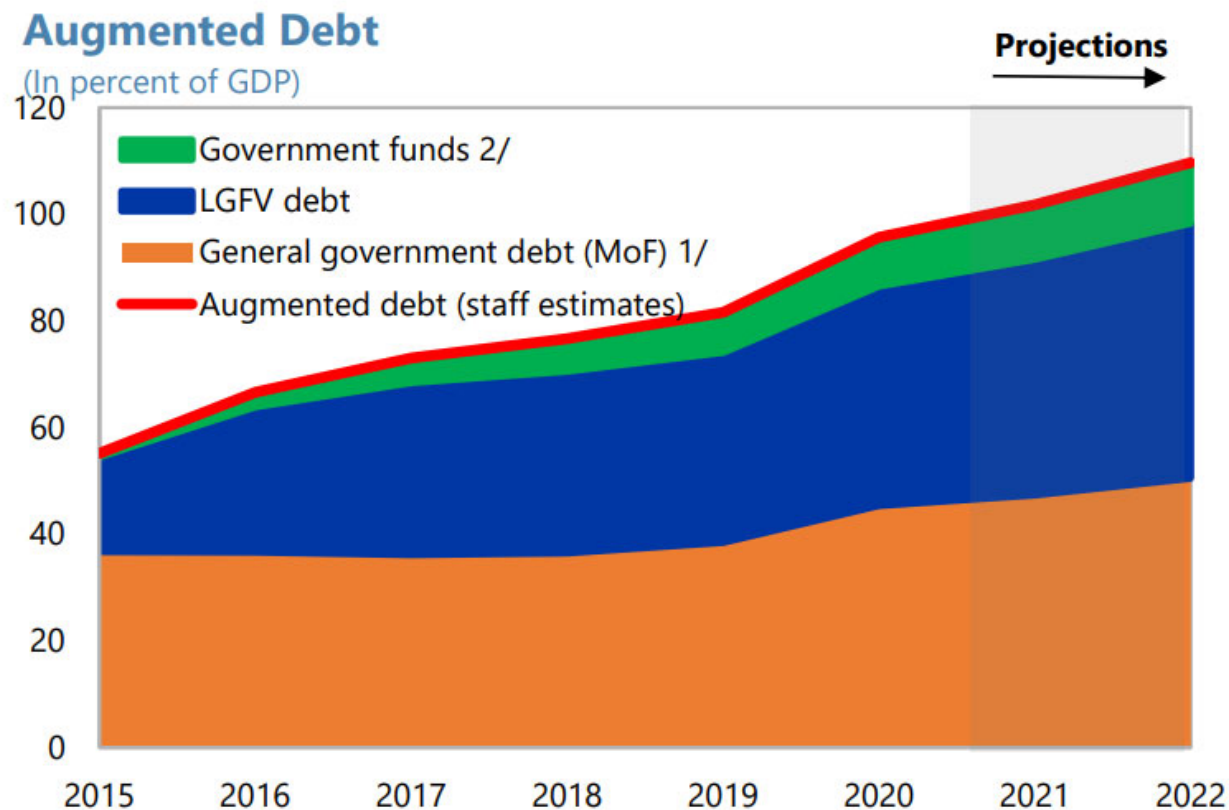
# The U.S. has imposed punishing export controls on Chinese chipmakers like YMTC and SMIC



# Foreign chip firms have almost completely halted investments in China



# China wants self-sufficiency, but mastering chipmaking technology will take years—and cost billions



Sources: Ministry of Finance (MoF); and IMF staff calculations.

1/ Data through 2020, 2021 estimated, 2022 projection.

2/ Government guided funds and special construction funds (social capital portion only).

# As tensions intensify, they may not only stay in the technological sphere

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## US to probe claims that top Chinese chipmaker violated ban on Huawei

YMTC said to have sold semiconductors that incorporated American technology to smartphone maker



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### Politics

## Top Economist Urges China to Seize TSMC If US Ramps Up Sanctions

- Policy proposal made in speech on US-China relations
- Research group overseen by China's economic planning agency

## Rubio, McCaul Demand Tougher Protections Against Chinese Semiconductor Maker SMIC, Warn of Possible Beijing-Moscow Coordination

MAR 17 2022

**Washington, D.C.** — U.S. Senator Marco Rubio (R-FL) and U.S. Representative Michael McCaul (R-TX) sent a letter to U.S. Department of Commerce Secretary Gina Raimondo urging the Department to strengthen Entity List rules for China's Semiconductor Manufacturing International Corporation (SMIC) and expressing concern that Beijing may divert technology to Moscow to evade U.S. sanctions. Their letter follows requests in [March 2021](#) and [December 2020](#).

"We have written to the Commerce Department twice to express these concerns, imploring the department to take all steps necessary to strengthen American economic security," **the lawmakers wrote**. "Since our last communication on the topic in March 2021, SMIC has posted record earnings, announcing soaring profits



## 4. How Supply Chains are Shifting

# Meanwhile, supply chains are shifting, driven by governments and companies



- The CHIPS and Science Act will spend \$39B on fabrication incentives, \$11B on R&D and around \$2B on other chip programs
- DARPA's Electronics Resurgence Initiative is funding new techniques for chip design, security, RF and other topics
- The Commerce Department has imposed new controls on tech transfer abroad

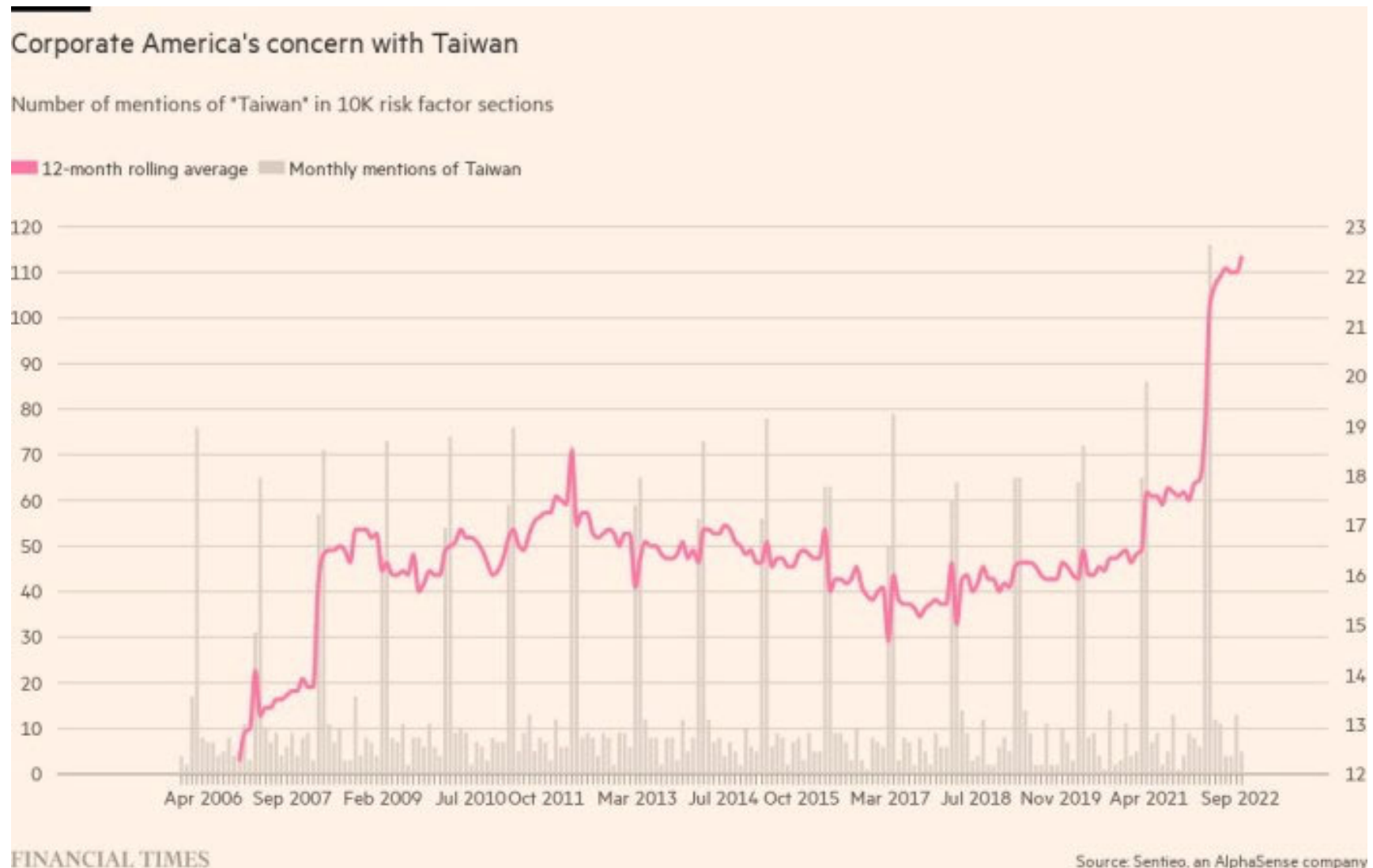
# Chips funding around the world

- **India** – subsidizing lagging-edge fabrication as well as design and materials
- **European United** – preparing a ~40-50 billion Euros Chips Act
- **Japan** – supporting new fabs such as TSMC's new facility
- **Taiwan** – providing a new 25% tax credit for R&D
- **South Korea** – considering a 25% tax credit on capital investment

# Capital expenditure on chips has skyrocketed



# Governments aren't the only player. Companies are worried about Taiwan risk.



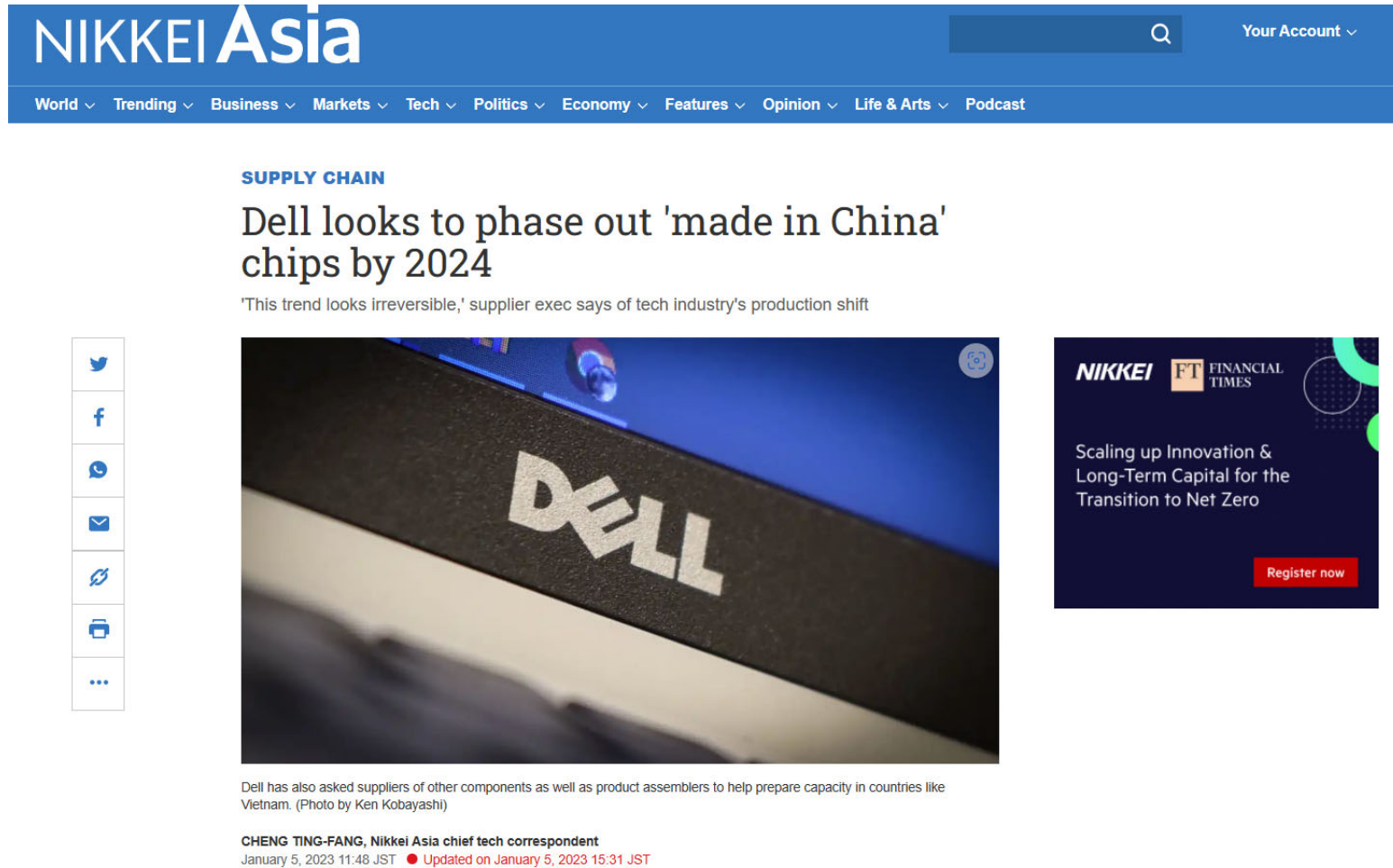
# TSMC, the world's largest chipmaker, is building new fabs in the U.S., Japan, and probably Germany



*TSMC's new facility in Arizona.*



# Electronic device makers are reducing use of Chinese components and China-based assembly





# Electronics assembly continues to shift toward Vietnam

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## Apple will reportedly begin producing some MacBooks in Vietnam in 2023 as it shifts from China

PUBLISHED TUE, DEC 20 2022•9:04 AM EST | UPDATED TUE, DEC 20 2022•4:00 PM EST



Ashley Capoot  
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### KEY POINTS

- Apple will begin producing some of its MacBook computers in Vietnam, according to a Nikkei Asia report.
- The move reflects the tech giant's continued push to expand its manufacturing beyond China.






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# Countries with limited electronics industries, like Mexico, are attracting attention


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## Notebook brands eye Mexico as possible production hub

Aaron Lee, Taipei;  
Eifeh Strom,  
DIGITIMES Asia

|  Tuesday 23 August 2022 |  0  Like 0


   




### Global wafer foundry industry analysis and forecast, 2022


An optimistic outlook on the global foundry industry through 2022

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### BIZ FOCUS



 Jan 12, 09:25

#### iCatch Technology's AI



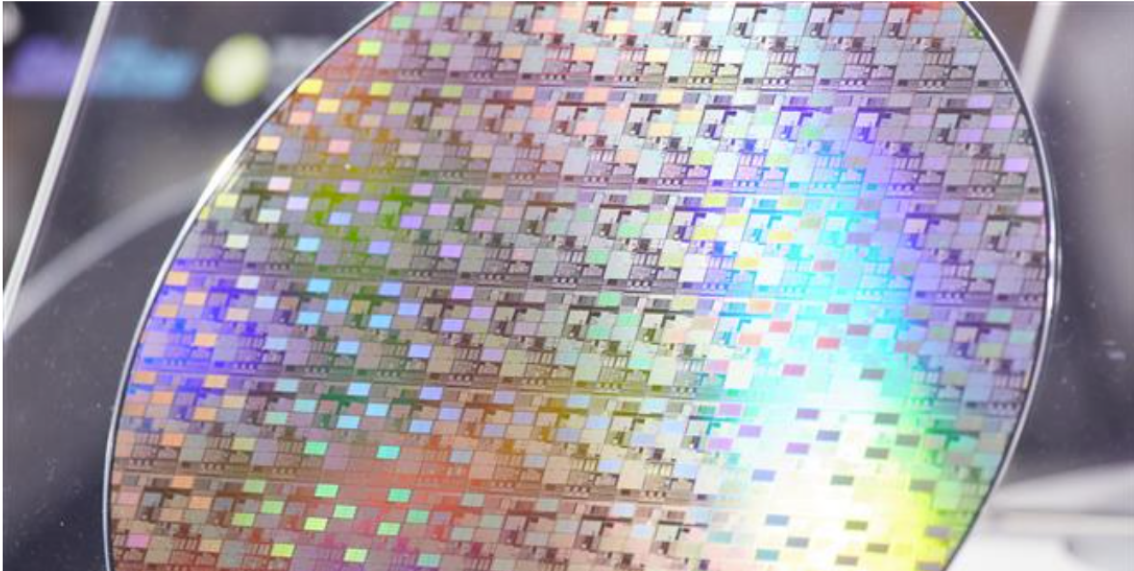
# Even India is attracting attention—and pouring in government funds

**DIGITIMESasia** TECH EV ASIA INNOVATIONS RESEARCH OPINIONS

## India reportedly to approve Vedanta-Foxconn's chip fab project

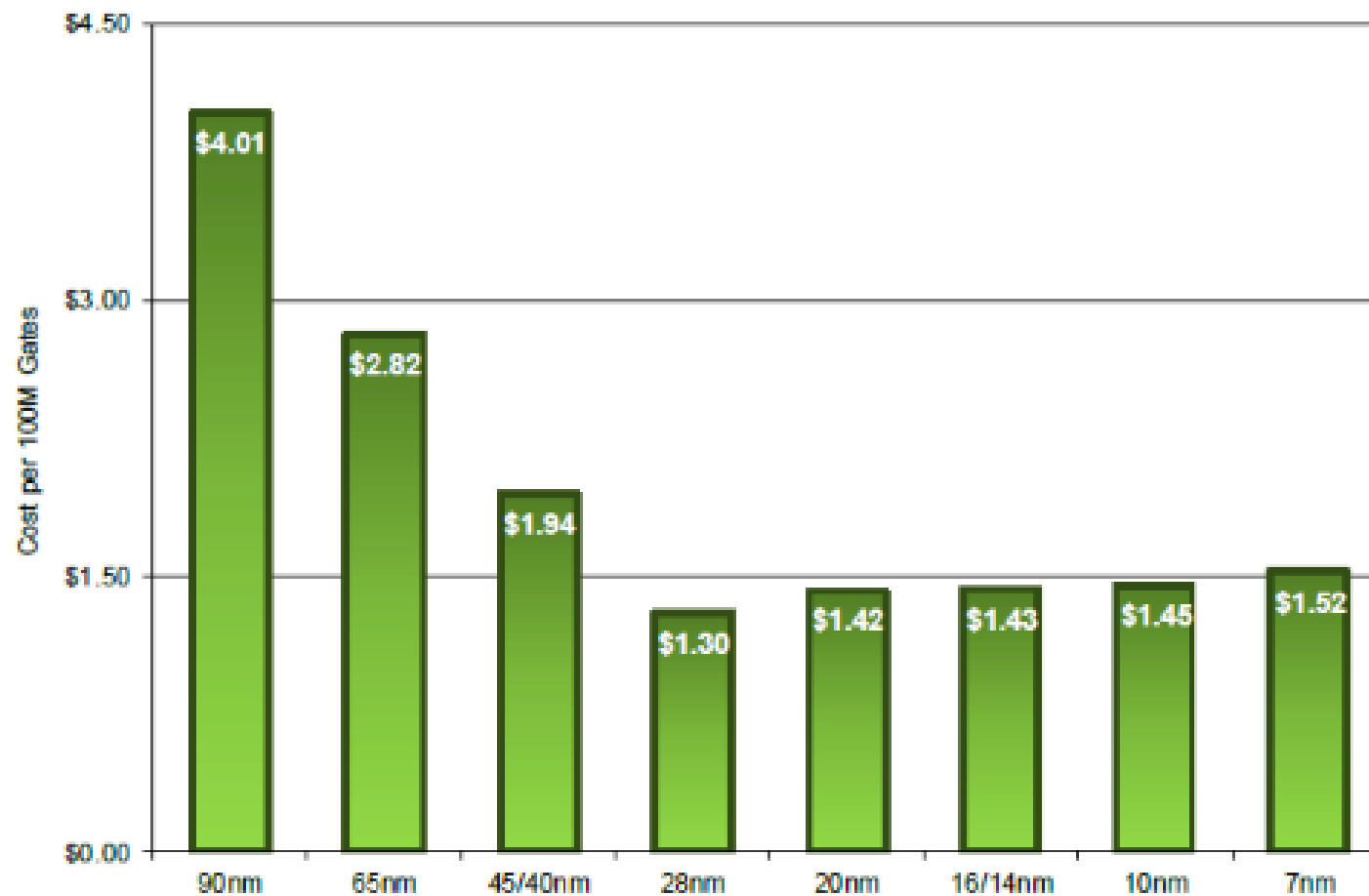
Jingyue Hsiao, DIGITIMES Asia, Taipei | ⌚ Thursday 12 January 2023 | 💬 0 👍 Like 0

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## 5. How the Chip Industry is Changing

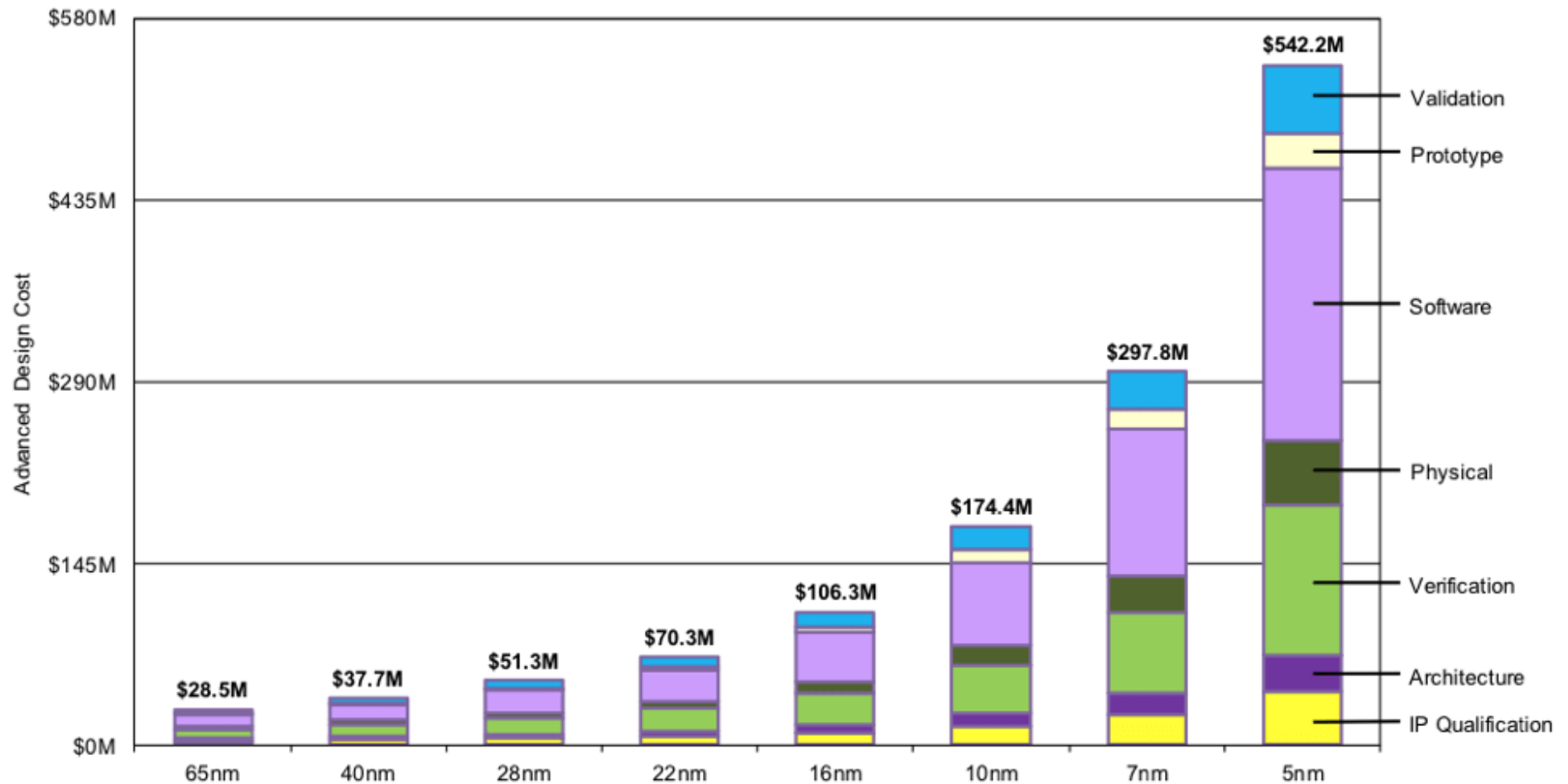
# Moore's law has stopped delivering lower costs per transistors



Source: International Business Strategies, Inc.



# Even designing leading edge chips is getting brutally expensive



**Open sources architectures like RISC-V reduce IP costs,  
so are growing rapidly**

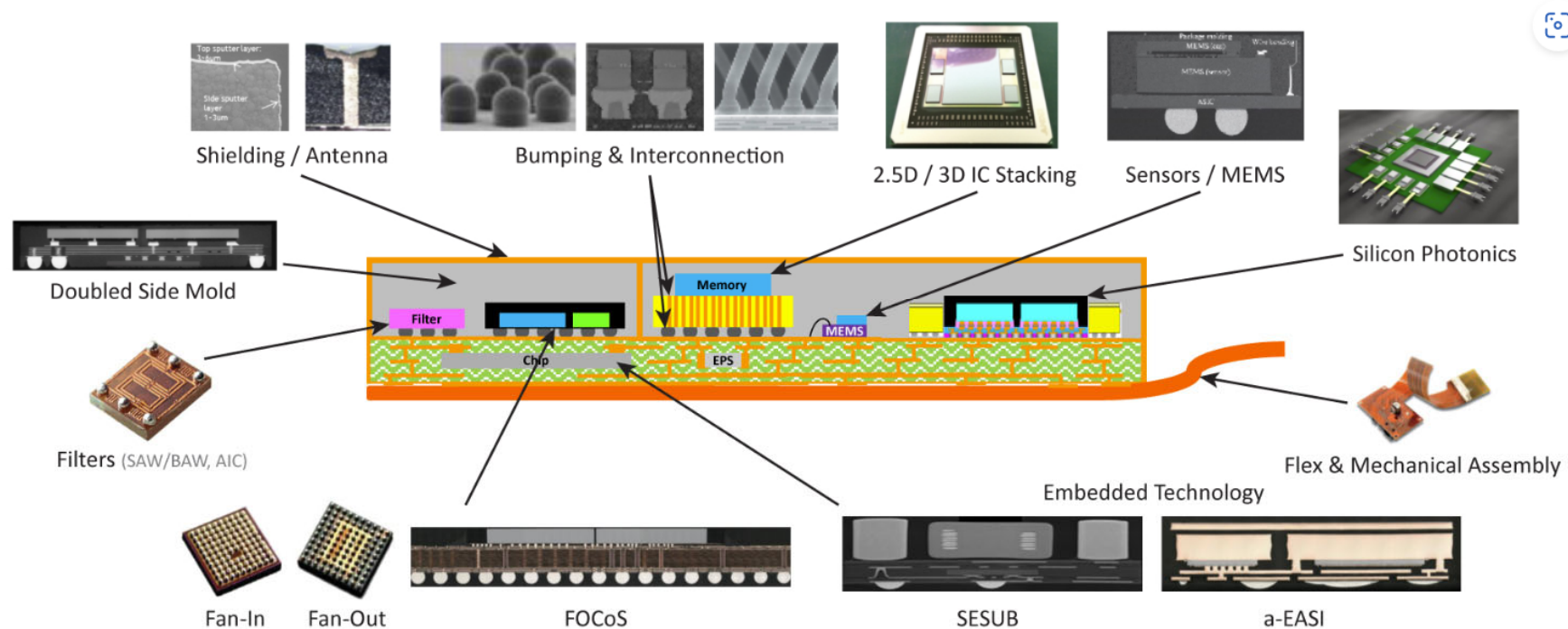


# The computational demands of training AI requires new architectures and better interconnects

- Nvidia and AMD GPUs continue to displace traditional x86 CPUs in datacenters
- Intel's newest datacenter chips like Sapphire Rapids involve substantial accelerators
- Chip design startups like Cerebras or Groq are mostly focused on designing ASICs for AI
- Amazon, Google and other cloud firms are investing heavily on chip design

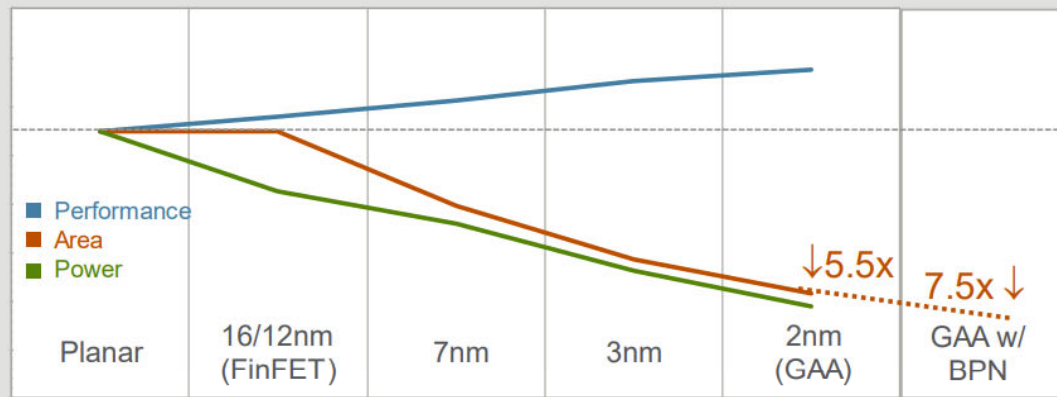
# The solution is heterogenous integration of leading and lagging edge chips and features like RF and photonics

## Technology Building Blocks for Heterogeneous Integration

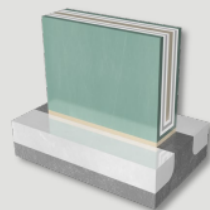


# As well as new packaging technologies like backside power delivery

## GAA with Backside Power Network for Additional Area Scaling

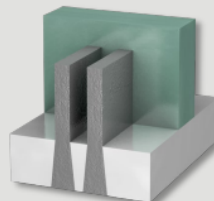


20 to 30% cell area reduction with Backside Power Network



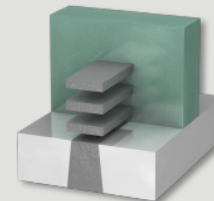
Planar

Intrinsic scaling  
+ 40% DTCO



5<sup>th</sup> Gen FinFET (5nm)

Intrinsic scaling  
+ >50% DTCO



GAA or Variants (2nm)

20-30% area scaling from DTCO



GAA with Backside Power Network

BPN: Backside Power Network

Applied Materials External

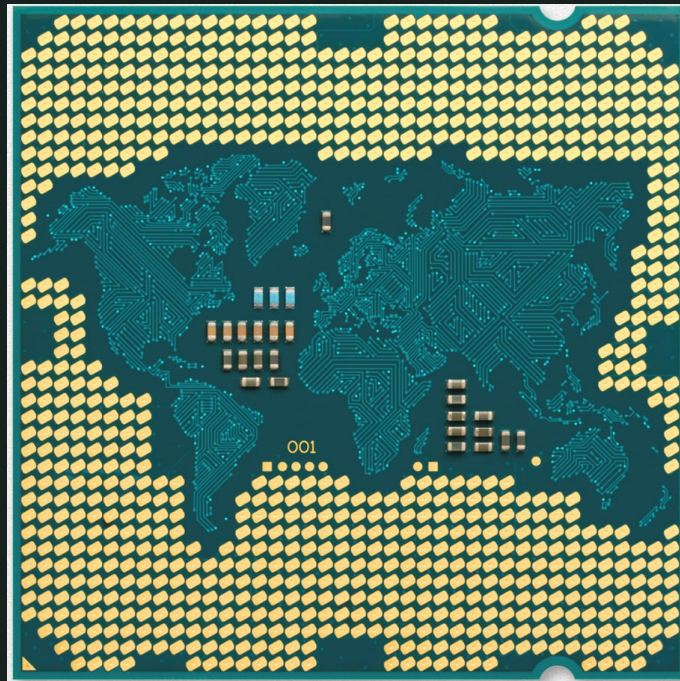




## 6. Implications for Japan

# Implications and Conclusions

1. Datacenters and cloud capabilities will be a key driver of semiconductor demand growth
2. Autos are a second major growth segment, requiring more communications and processing capabilities
3. The traditional era of Moore's Law is being replaced by a more differentiated landscape, in which a combination of chip design, software, packaging, and interconnect capabilities will drive progress
4. Tech firms must adapt to technological shifts while de-risking supply chains from excessive dependence on China or Taiwan



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